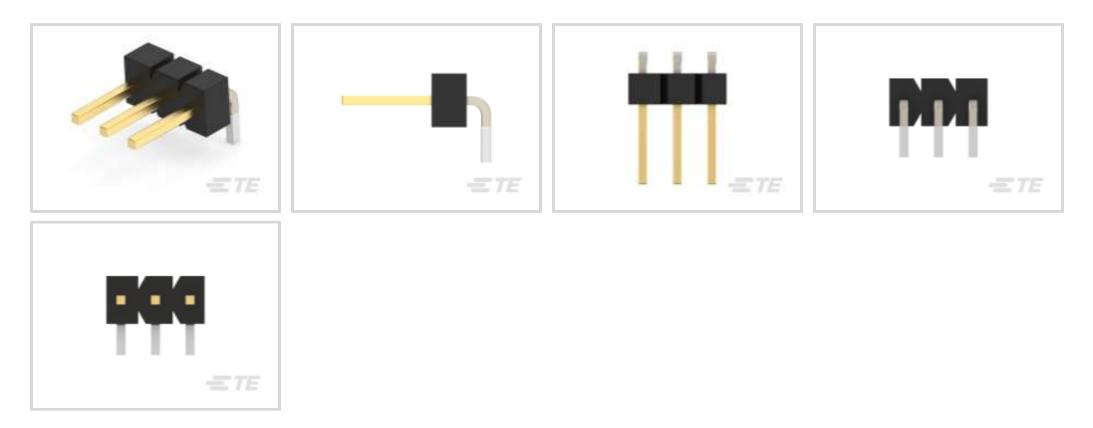
5-103765-3 - ACTIVE

AMPMODU

TE Internal #: 5-103765-3 PCB Mount Header, Right Angle, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, Black

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board

Number of Positions: 3

Number of Rows: 1

Features

connectivity

Product Type Features

	00/02/2022 10.5
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Features	
Primary Product Color	Black
Body Features	
Board-to-Board Configuration	Perpendicular
Number of Rows	1
Number of Positions	3
PCB Mount Orientation	Right Angle
Configuration Features	
Connector & Contact Terminates To	Printed Circuit Board
Sealable	No
Header Type	Breakaway
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header

5-103765-3

PCB Mount Header, Right Angle, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, Black



Contact Underplating Material Thickness1.27 μm[50 μin]PCB Contact Termination Area Plating Material FinishMatteContact Shape & FormSquareContact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinPCB Contact Termination Area Plating MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePinContact Current Rating (Max)3 ATermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount AlignmentWithoutPCB Mount AlignmentWithout		
Contact Shape & FormSquareContact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinContact Base MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePinContact Current Rating (Max)3 ATermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinContact Base MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePinContact Current Rating (Max)3 ATermination FeaturesTermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	PCB Contact Termination Area Plating Material Finish	Matte
PCB Contact Termination Area Plating MaterialTinContact Base MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePinContact Type3 AContact Current Rating (Max)3 ATermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Shape & Form	Square
Contact Base MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 µm[30 µin]Contact TypePinContact Current Rating (Max)3 ATermination FeaturesTermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Underplating Material	Nickel
Contact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePinContact Current Rating (Max)3 ATermination FeaturesThrough Hole - SolderTermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness.76 µm[30 µin]Contact TypePinContact Current Rating (Max)3 ATermination FeaturesThrough Hole - SolderTermination Method to Printed Circuit BoardThrough Hole - SolderMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Base Material	Copper Alloy
Contact TypePinContact Current Rating (Max)3 ATermination FeaturesTermination Method to Printed Circuit BoardThrough Hole - SolderMechanical AttachmentVithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithoutPCB Mount AlignmentWithout	Contact Mating Area Plating Material	Gold
Contact Current Rating (Max)3 ATermination FeaturesThrough Hole - SolderTermination Method to Printed Circuit BoardThrough Hole - SolderMechanical AttachmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Termination Features Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without	Contact Type	Pin
Termination Method to Printed Circuit BoardThrough Hole - SolderMechanical AttachmentVithoutMating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Contact Current Rating (Max)	3 A
Mechanical Attachment Without Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without	Termination Features	
Mating AlignmentWithoutPCB Mount RetentionWithoutPCB Mount AlignmentWithout	Termination Method to Printed Circuit Board	Through Hole - Solder
PCB Mount RetentionWithoutPCB Mount AlignmentWithout	Mechanical Attachment	
PCB Mount Alignment Without	Mating Alignment	Without
	PCB Mount Retention	Without
Connector Mounting Type	PCB Mount Alignment	Without
Connector Mounting Type Board Mount	Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>

5-103765-3

PCB Mount Header, Right Angle, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, Black



EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought



Documents

C For support call+1 800 522 6752

5-103765-3

PCB Mount Header, Right Angle, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, Black



CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-103765-3_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-103765-3_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-103765-3_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Environmental Compliance TE Material Declaration

English